Manual Update Sheet

MicroStar BGA Discontinued and Redesigned



Precision ADC

ABSTRACT

This document should be used in conjunction with the device data sheet and describes the updated package designator for the indicated devices.

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1 Package Redesign Details

Explanation

The devices in the MicroStar BGA™ packaging were redesigned using a laminate nfBGA package. The nfBGA package offers data sheet-equivalent electrical performance and data sheet-equivalent or better thermal performance. It provides the same X and Y dimensions as MicroStar BGA, and provides pin-to-pin and footprint compatibility. The nFBGA PCB land pattern and stencil recommendations have been updated to achieve better soldering results after extensive testing and evaluation. For more details, please refer to this nfBGA Package Application Report.

When referencing the device data sheet, use the new package designator in place of the discontinued package designator throughout the document.

The orderable addendum at the end of the device data sheet will reflect the new package designator.

See the following page or the end of the device data sheet for the updated nfBGA package drawing.

Table 1-1. Package Designator

Old Package Designator	New Package Designator	
ZQE	ZXH	
GQR	GVX	

Reason for Discontinuance

Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA and MicroStar Junior™ BGA packaging devices and offering a Last Time Buy.

These devices have now been converted to an nfBGA package.

Devices Affected

The following table describes the devices affected, the old and new package designators, and references to the device data sheet.

Table 1-2. Devices and Nomenclature

Device	Discontinued MicroStar BGA Device	Redesigned Laminate nfBGA Device	Device Data Sheet
TLV320AIC3106	TLV320AIC3106IZQER	TLV320AIC3106I ZXH R	SLAS509F
TLV320AIC33	TLV320AIC33I ZQE R	TLV320AIC33I ZXH R	SLAS480B
TLV320AIC33	TLV320AIC33I ZQE	LV320AIC33I ZXH	SLAS480B
TLV320AIC33	TLV320AIC33I GQE	TLV320AIC33I GVX	SLAS480B

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